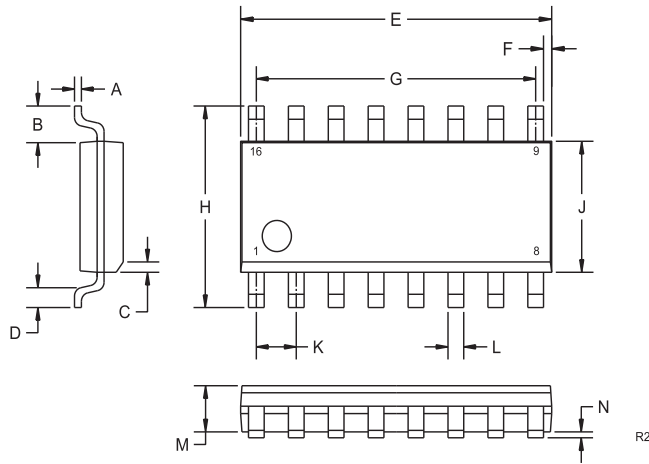


Package Details

SOIC-16 Case



Mechanical Drawing



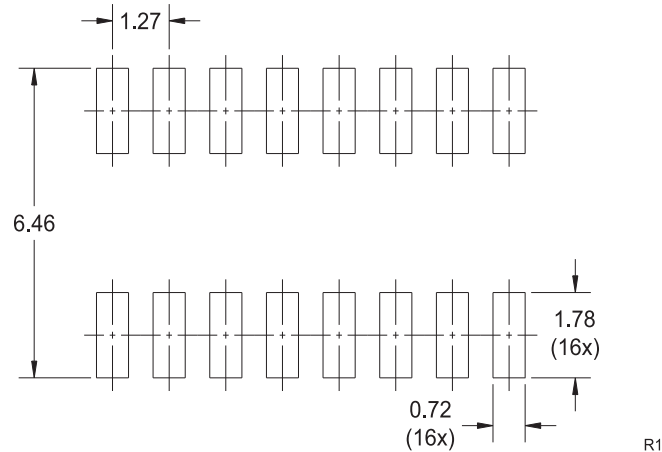
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.007	0.010	0.19	0.25
B	0.041		1.04	
C	0.010	0.020	0.25	0.50
D	0.020	0.035	0.50	0.90
E	0.386	0.394	9.80	10.00
F	0.010		0.25	
G	0.350		8.89	
H	0.228	0.244	5.80	6.20
J	0.150	0.157	3.80	4.00
K	0.050		1.27	
L	0.0138	0.0201	0.35	0.51
M	0.0531	0.0689	1.35	1.75
N	0.0039	0.0098	0.10	0.25

SOIC-16 (REV:R2)

Lead Code:
Reference individual
device datasheet.

Part Marking: Full Part Number

Mounting Pad Geometry (Dimensions in mm)



R1

R2 (4-March 2010)

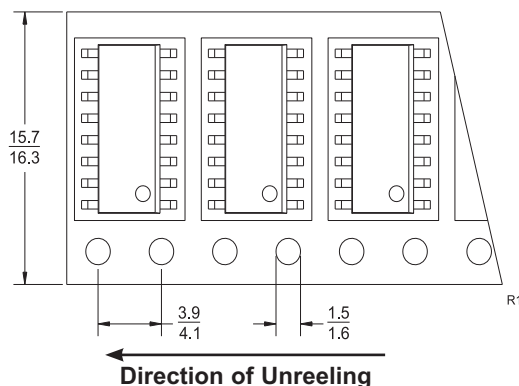
Package Details

SOIC-16 Case



Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 16mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-2-A

Packaging Base

13" Reel = 2,500 pcs.

Reel Labeling Information

Each reel is labeled with the following information:

Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
13"	4	10,000	15x4x15	38x10x38	8	4
	9	22,500	15x15x9	38x38x23	17	8
	18	45,000	15x15x18	38x38x46	33	15

Ordering Information

- For devices taped and reeled on 13" reels, add TR13 suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R2 (4-March 2010)

Material Composition Specification

SOIC-16 Case



Device average mass 145 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.66%	3.86	Si	7440-21-3	2.66%	3.86	26,621
bond wire	gold	0.28%	0.4	Au	7440-57-5	0.28%	0.4	2,759
leadframe	copper	31.38%	45.5	Cu	7440-50-8	31.38%	45.5	313,793
die attach	silver epoxy	0.3%	0.44	Ag	7440-22-4	0.24%	0.35	2,414
				epoxy resin	Proprietary	0.06%	0.09	621
encapsulation	EMC	63.79%	92.5	silica (fused)	60676-86-0	44.9%	65.1	448,966
				epoxy resin	Proprietary	15.86%	23.0	158,621
				Sb ₂ O ₃	1309-64-4	1.24%	1.8	12,414
				TBBA	79-94-7	1.52%	2.2	15,172
				carbon	1333-86-4	0.28%	0.4	2,759
plating*	tin/lead process	1.59%	2.3	Sn	7440-31-5	1.34%	1.95	13,448
				Pb	7439-92-1	0.24%	0.35	2,414
	matte tin	1.59%	2.3	Sn	7440-31-5	1.59%	2.3	15,862

*For Lead Free plating, add suffix "LEAD FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R2 (3-June 2011)